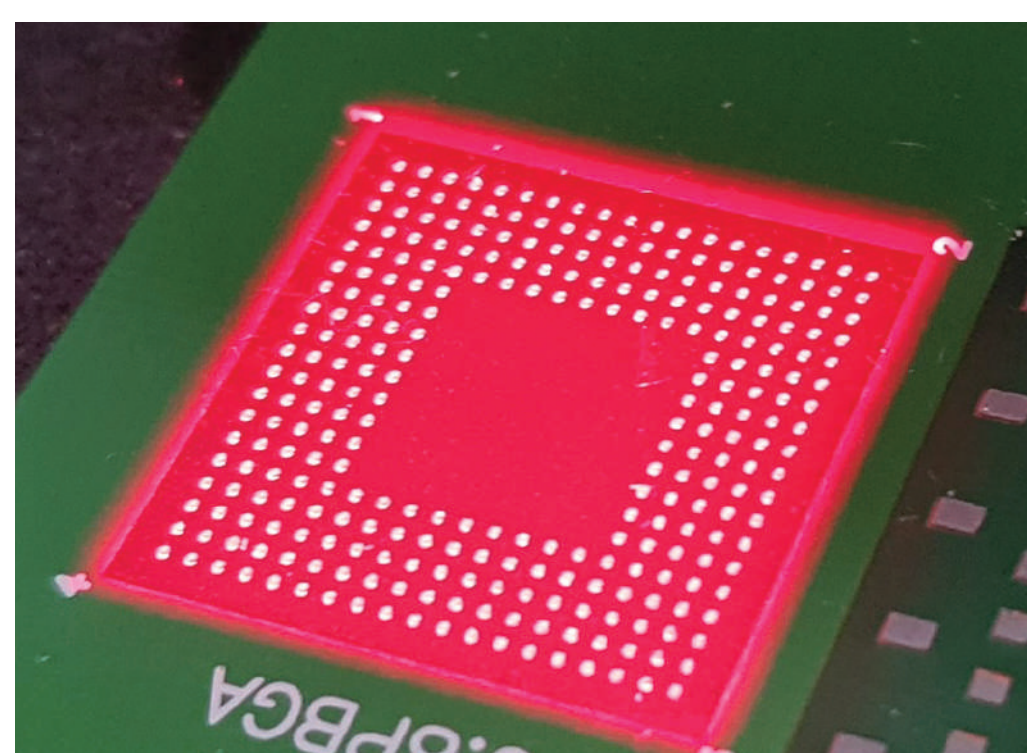


加熱時の基板、部品の反り低減へ

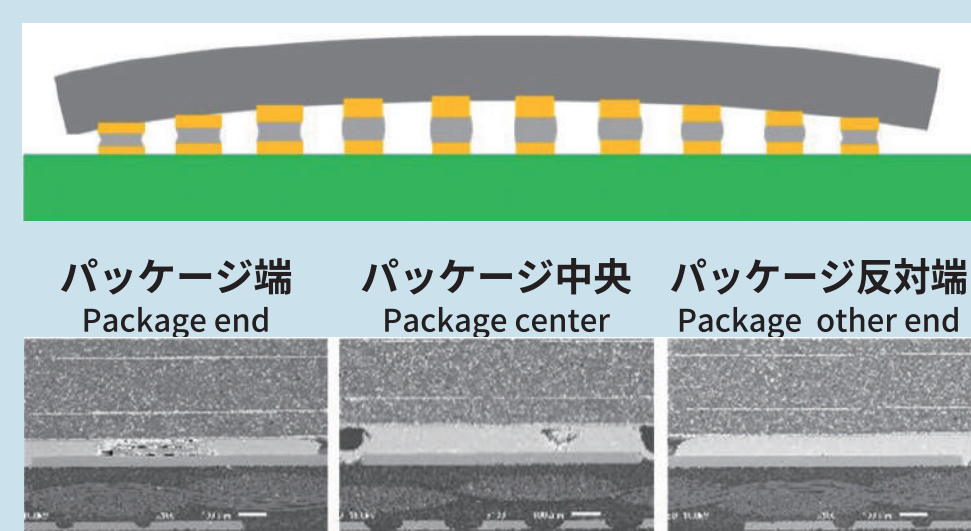
To reduce warpage of boards and components during heating

短時間、局所均一加熱のエリアレーザー対応はんだペースト

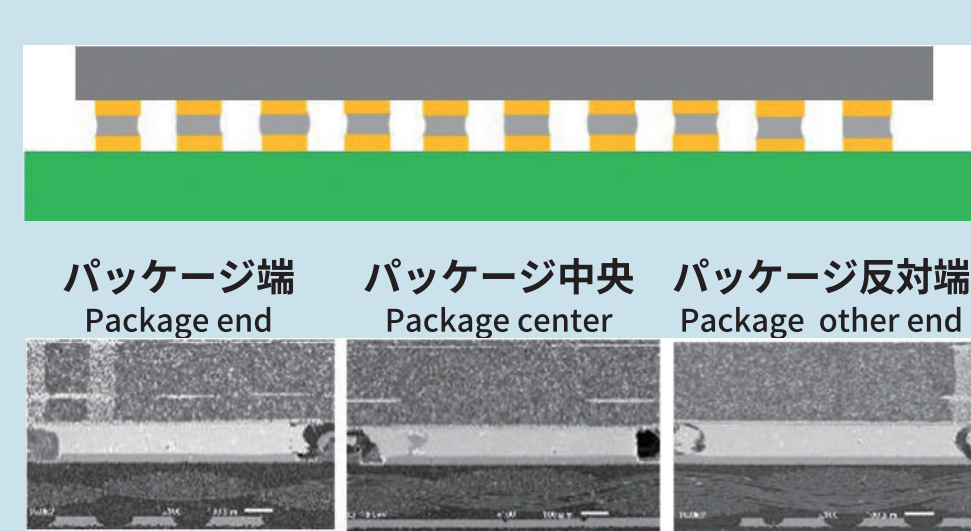
Solder Paste for area laser processing for short-time, localised uniform heating.



従来のリフロー加熱による接合状態
Joining conditions with conventional reflow heating.



エリアレーザー加熱による接合状態
Joining conditions with area laser heating.



エリアレーザー加熱対応はんだペースト

Solder paste for Area-Laser heating

NP303-COSMO-LA501-T4

急加熱での良好なはんだ付け性 (低飛散、良好な濡れ性)
Excellent solderability under rapid heating (low scattering, Excellent wettability)

短時間での良好な接合品質確保 (合金層形成、低ボイド)
Excellent solder joint quality in a short time
(Inter Metallic compound formation, low void rate)

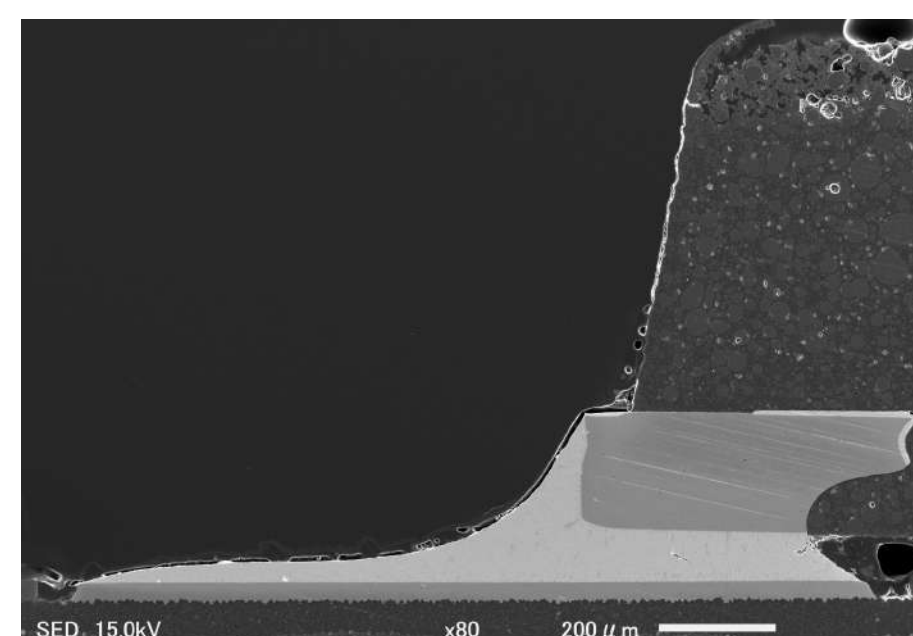
常温輸送、常温保管が可能
Can be transported and stored at room temperature

短時間加熱で良好なはんだ接合

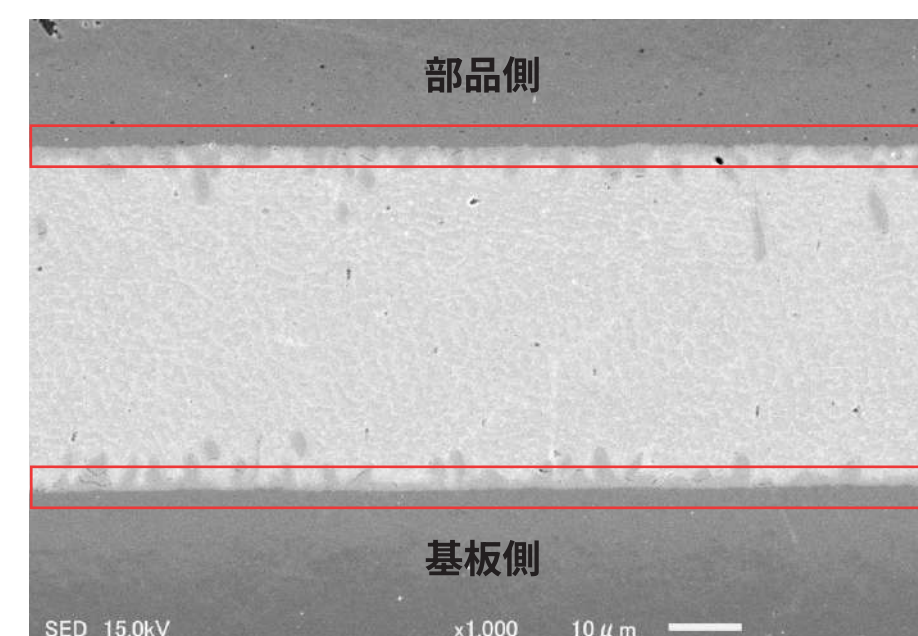
Excellent solder joints with short heating time

QFN部品接合断面

QFN component joint cross-section



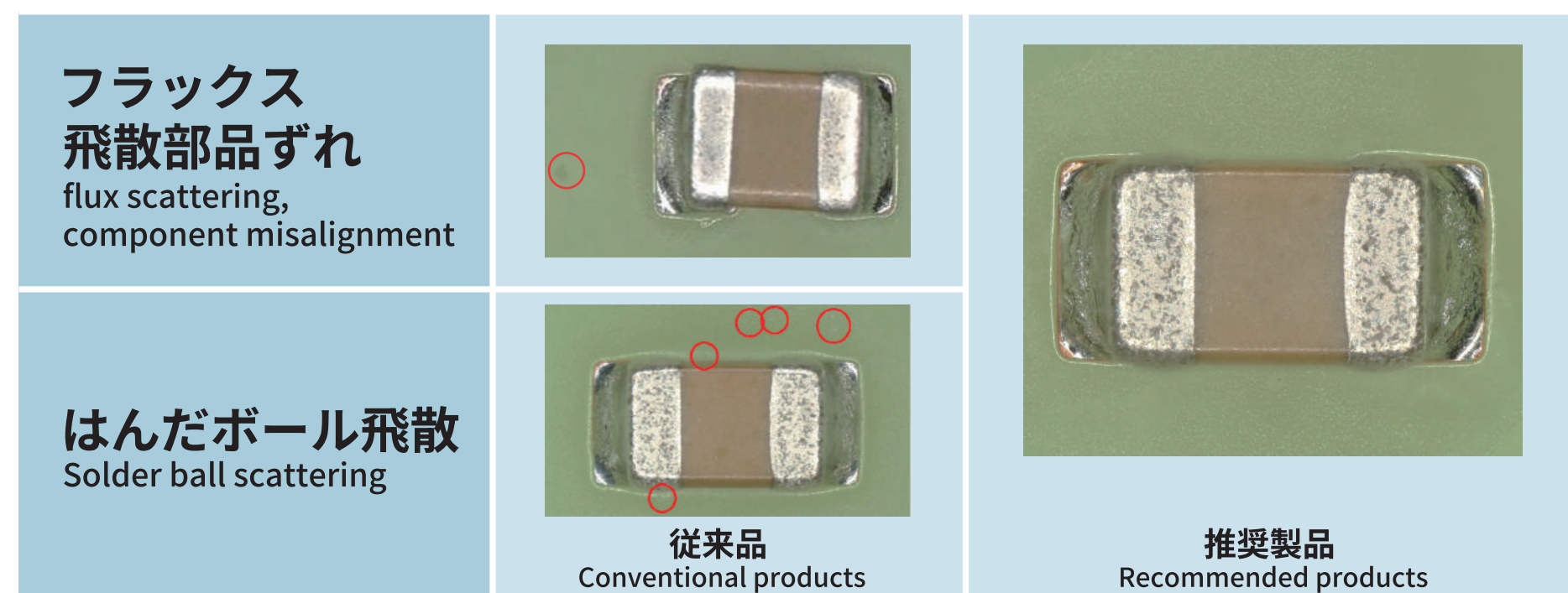
端子電極はんだ接合部
Terminal electrode solder joint



部品側
基板側
接合部界面拡大
Inter Metallic Compound formation at board side and component side

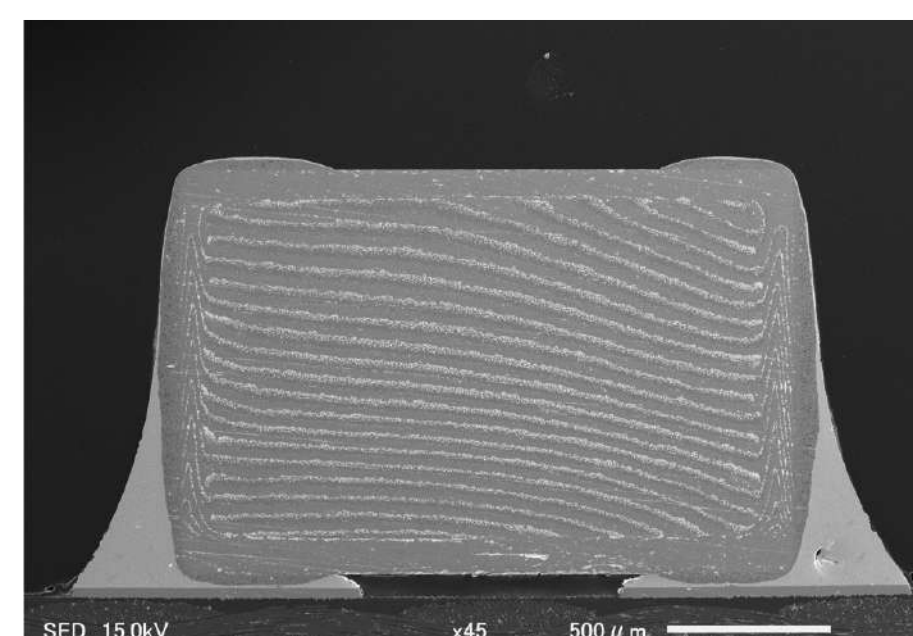
急加熱によるフラックス、 はんだボール飛散低減

Reduced flux and solder ball scattering due to rapid heating.

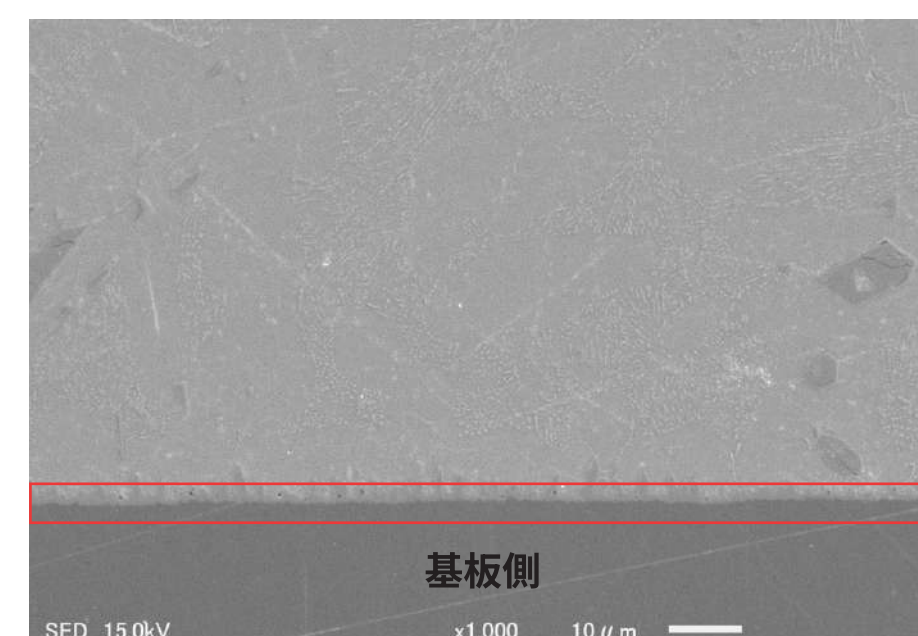


MLCC部品接合部断面

MLCC component joint cross-section joints



部品全体はんだ接合部
Whole component solder joint

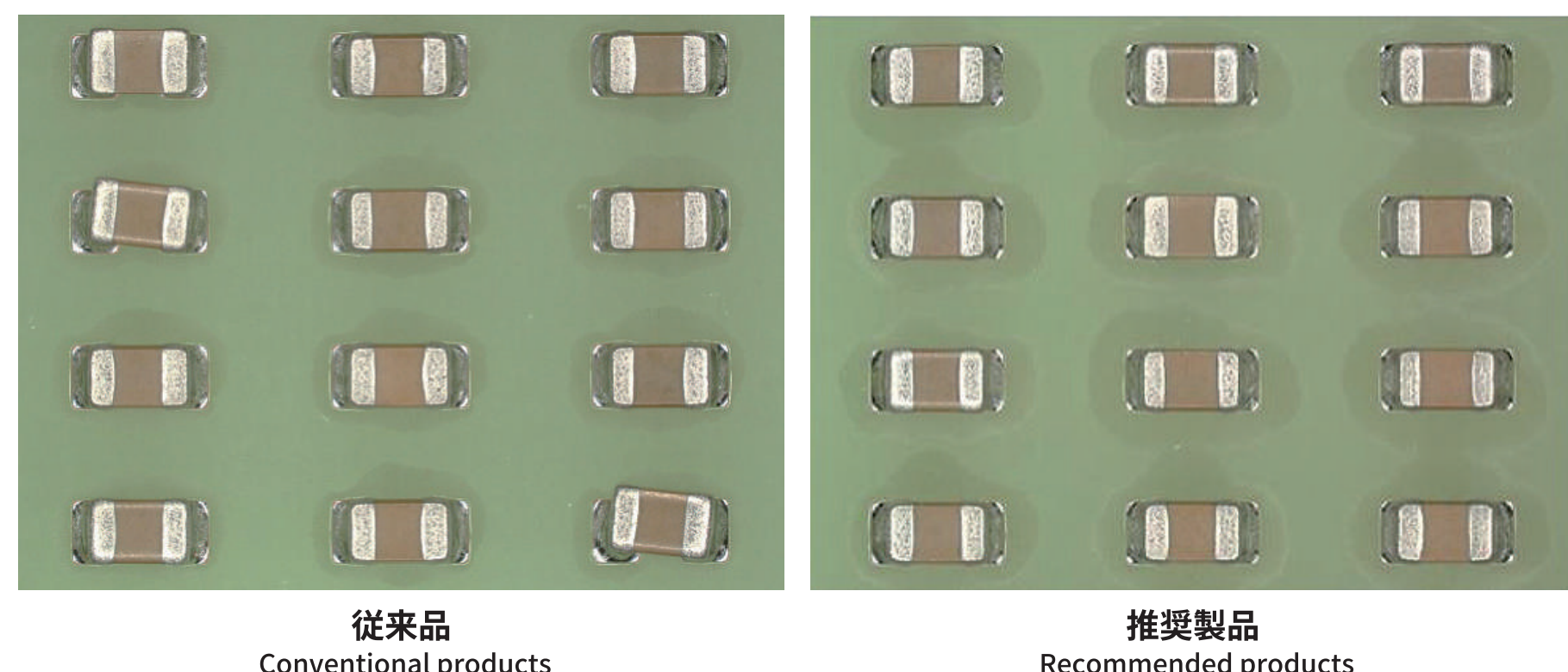


接合部界面拡大
Inter Metallic Compound formation at board side

基板、部品電極間のはんだ付け後の合金拡散層形成確認
Confirmation of Inter Metallic Compound formed after soldering between board and component electrodes.

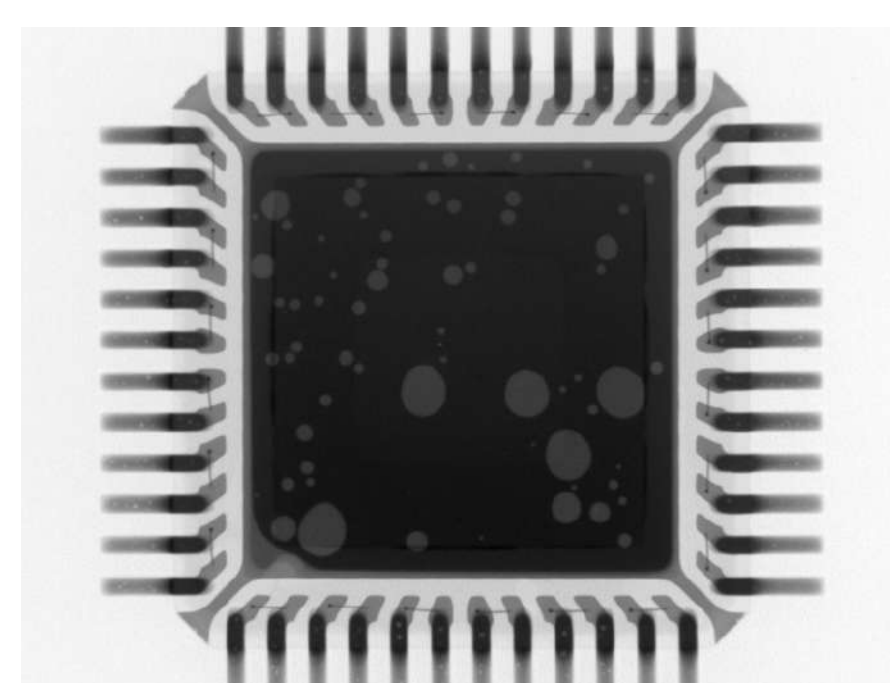
短時間加熱ながら セルフアライメント性能確保

Ensures self-alignment performance despite short heating time

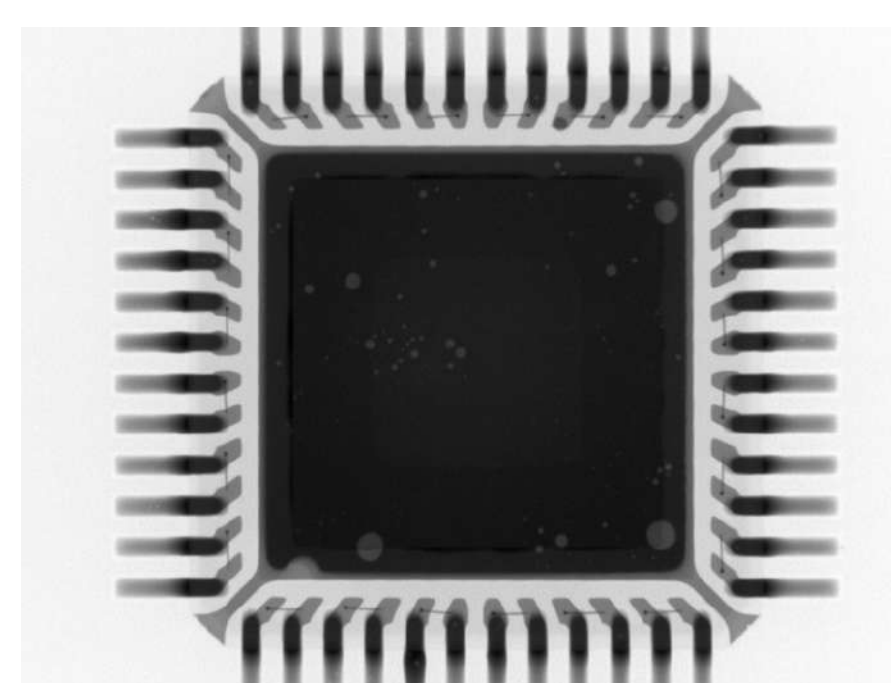


ボイド抑制

Low void rate



リフロー加熱による従来製品
Conventional products by reflow oven heating



エリアレーザー加熱による推奨製品
Recommended products by area laser heating

